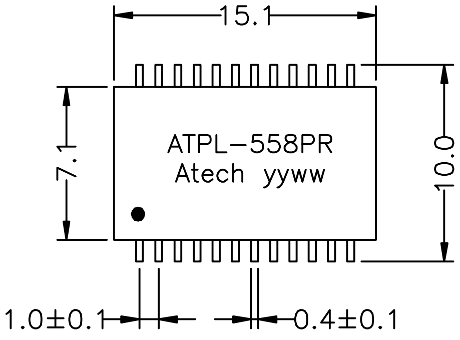
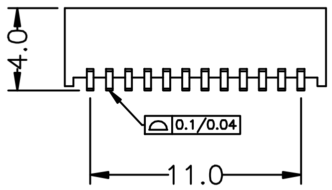
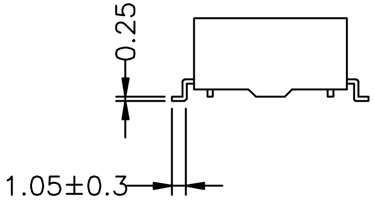
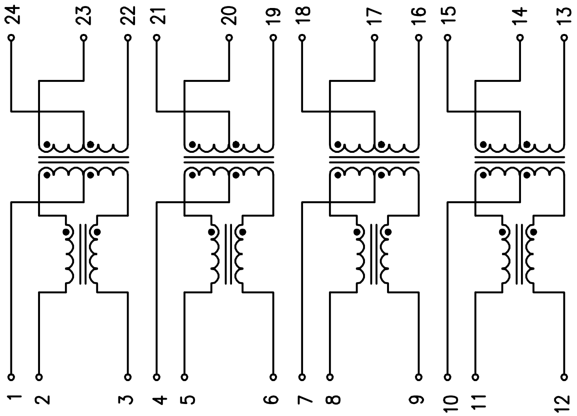




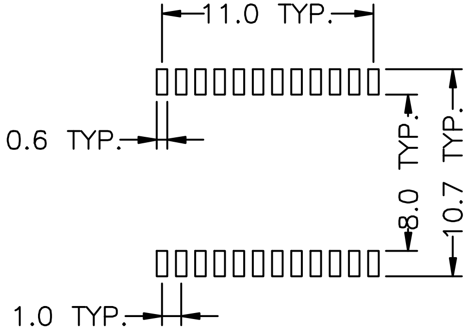




* RoHS COMPLIANT

ELECTRICAL CHARATERISTICS@25°C

1. OCL : (@100kHz, 0.1V, 8mA DC Bias) : 180uH MIN.
2. DCR : 1.0Ω MAX.
3. TURNS RATIO : 1CT : 1CT ±5%
4. INSERTION LOSS : (@1–50MHz) : –0.5dB MAX.
   (@50–125MHz) : –1.0dB MAX.
   (@125–200MHz) : –2.0dB MAX.
5. RETURN LOSS : (@1–40MHz) : –20dB MIN.
   (@40–100MHz) : –16dB MIN.
   (@100–150MHz) : –12dB MIN.
   (@150–200MHz) : –10dB MIN.
6. CROSS TALK : (@1–125MHz) : –30dB MIN.
   (@125–200MHz) : –25dB MIN.
7. COMMON MODE REJECTION : (@1–125MHz) : –30dB MIN.
   (@125–200MHz) : –20dB MIN.
8. ISOLATION HIPOT : (@1500VAC, 1mA, 60S)
9. Comply with IEEE802.3bz & 802.3at
10. Suitable for End–span PoE applications with 720mA current capability
11. OPERATING TEMPERATURE : 0°C TO +70°C
12. STORAGE TEMPERATURE : –25°C TO +105°C



SUGGESTED PAD LAYOUT

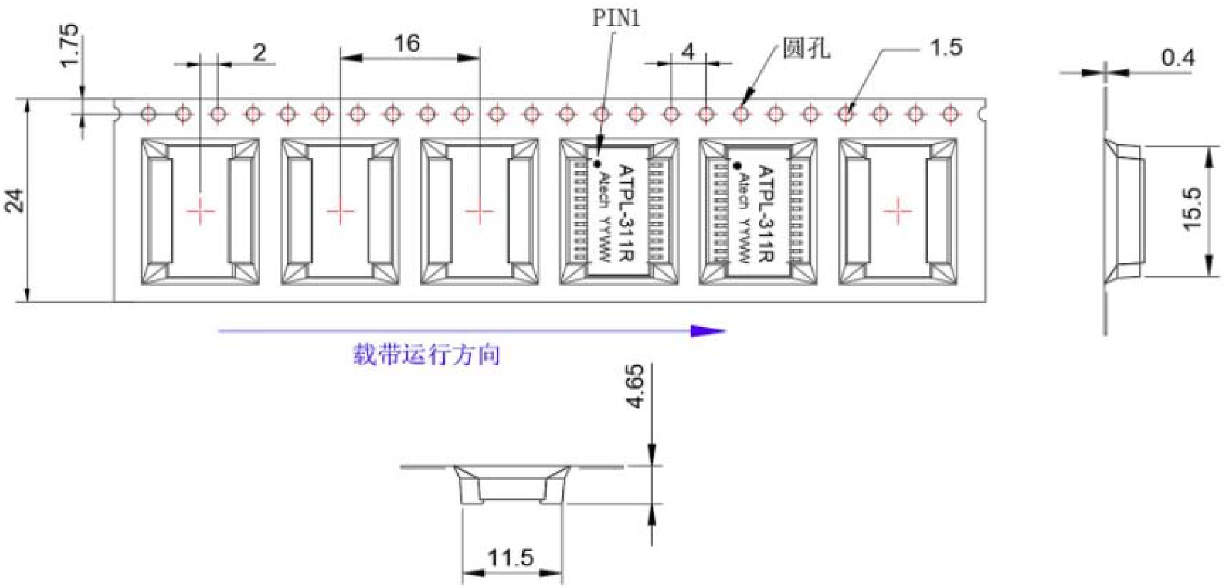
UNLESS OTHERWISE SPECIFIED ALL TOLERANCES ARE ±0.25mm

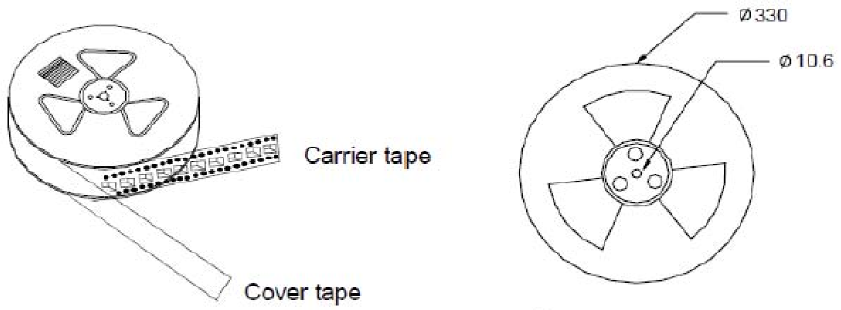
	RELEASE	05/09 /2022	SHIRLEY	BETTY	BETTY
NO:	DESCRIPTION	DATE	BY	CHK	APPD
REVISIONS					

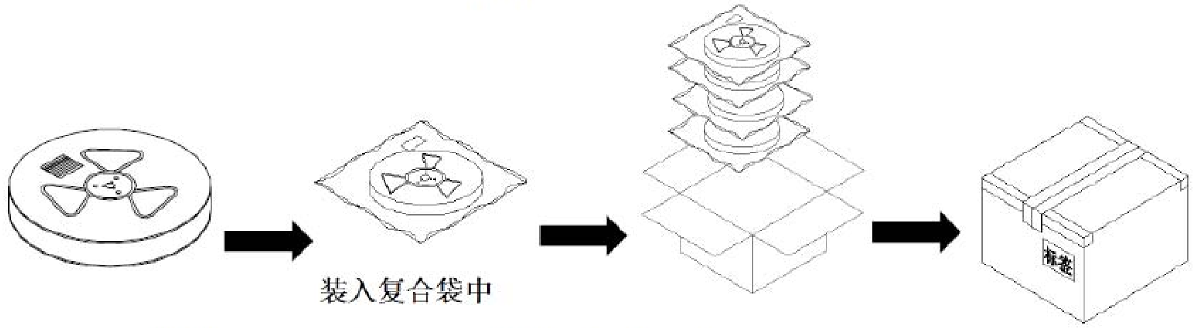
AOEM Atech

TITLE 2.5G BASE–T TRANSFORMER		
DWG. NO. ATPL–558PR		
UNITS: M/M	SAFETY	SHEET 1 OF 1
DATE 05/09/22	P/N:	DRAW SHIRLEY

3. Package :





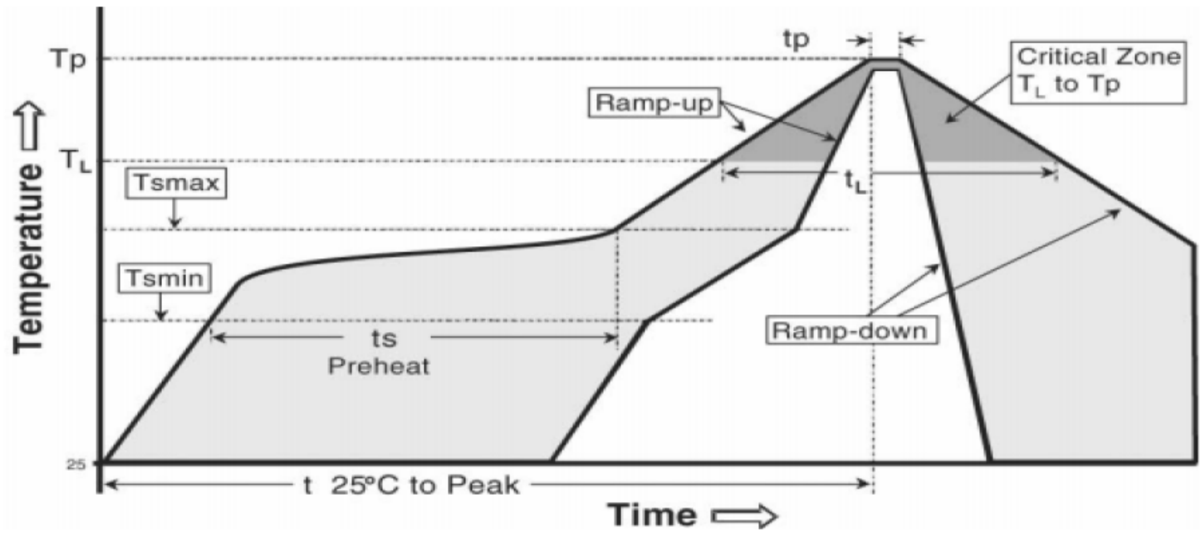


装入复合袋中

零件包装符合EIA-481 standard(拉力 0.26N~1.3N)

Product	PCS/Reel	PCS/Box	Product No.	Weight(g/pcs)
SMD 24 PIN Series	800	800x8=6400		

5. Pb-free Soldering Heat Withstanding Survey (SMD)



reflow profile

Form-1（Reference JEDEC J-STD-020D Table 5-2））

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate （Tsmax to Tp）	3°C/second max	3°C/second max
Preheat Temperature Min（Tsmin） Temperature Min（Tsmax） Time（Tsmin to Tsmax）（ts）	100°C 150°C 60-120seconds	150°C 200°C 60-180seconds
Time maintained above Temperature（TL) Time（tL)	183°C 60-150seconds	217°C 60-150seconds
Peak Temperature（Tp）	225℃	260℃
Time within 5°C of actual Peak Temperature（Tp)^2	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max